

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: CHEN, Chih-Ming Conf.:
Appl. No.: NEW Group:
Filed: July 25, 2002 Examiner:
For: SOLDER BUMP FABRICATION METHOD AND APPARATUS

L E T T E R

Assistant Commissioner for Patents
Washington, DC 20231

COPY

July 25, 2002

Sir:

Under the provisions of 35 U.S.C. § 119 and 37 C.F.R. § 1.55(a), the applicant(s) hereby claim(s) the right of priority based on the following application(s):

<u>Country</u>	<u>Application No.</u>	<u>Filed</u>
TAIWAN, R.O.C.	90125268	October 12, 2001

A certified copy of the above-noted application(s) is(are) attached hereto.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional fee required under 37 C.F.R. §§ 1.16 or 1.17; particularly, extension of time fees.

Respectfully submitted,

BIRCH, STEWART, KOLASCH & BIRCH, LLP

By

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KM/jaf
0941-0506P

Attachment